December 5, 2022

Mitsui Kinzoku Exhibits at Advanced Packaging and Chiplet Summit (APCS) 2022

Mitsui Mining & Smelting Co., Ltd. (hereinafter, "Mitsui Kinzoku") will exhibit at the Advanced Packaging and Chiplet Summit (APCS) 2022 to be held on the three days from Wednesday, December 14, to Friday, December 16, 2022 at Tokyo Big Sight. Details are as follows:

APCS will be held in parallel with SEMICON Japan 2022, bringing together the latest technologies/solutions related to semiconductor packaging. Mitsui Kinzoku will showcase Cu sinter paste, a bonding material for next-generation power semiconductors. It is expected to be a highly reliable, high heat resistant and environmentally friendly (lead-free) material for power devices that must perform at high outputs with high reliability when used in EVs, power generation, transmission and distribution equipment, industrial equipment, etc. Moreover, the material can be sintered in a nitrogen environment making it applicable in existing Ag processes since its proprietary material design ensures heat conductivity of 190 W/ (m・K) and reliable operation at -55 to 150 degrees Celsius and 1,000 cycles.

We would appreciate your visiting the exhibit.

Attendees must register in advance (admission free) on the exhibition's website before coming to the venue.

■ Exhibition outline

Name of exhibition: Advanced Packaging and Chiplet Summit (APCS) 2022

Time and date: From 10:00 a.m. to 5:00 p.m. from Wednesday, December 14 to Friday, December 16, 2022

Venue: Tokyo Big Sight East Exhibition Hall

Mitsui Kinzoku booth: APCS:3953

Official website: https://www.semiconjapan.org/jp/apcs

Product being exhibited: Cu sinter paste for power semiconductor

Photo 1: Cu sinter paste

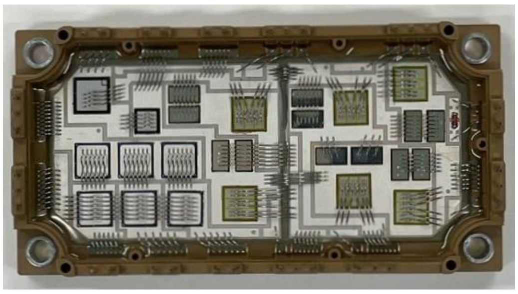

Photo 2: Power module test vehicle using Mitsui Kinzoku's

[Inquiries]

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